



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Manufacturing Info/ Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Chan, Nelson	Contact Title	Manager Sales, HKG SELL DIR-EMS		
Company Unique ID	TE Connectivity	Response Date	2015-12-11	Contact Email	nelson.chan@te.com				
Contact Phone Number	+852-2738-8751								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	1241050-5	Amount	849.26753	Version	-	Identity			
Manufacturer Item Name	2x5P MOD II BREAK AWAY HDR,SMD, BLISTER	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-1214	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Manufacturing Information									
J-STD-020 MSL Rating		Max Total a Wave Time		Ramp Rate		Wave Additional Info			
Classification Temp		Max Wave Solder Time	20.0	Ramp Down Rate		Psi Rating Reflow			
Max Time Within 5		Psi Rating Wave		Package Designator		Size	0.0		
Time Above 217		Reflow Additional Info		Preheat Max Temp		Terminal Base Alloy	NAC		
Preheat Duration		bulk Solder Termination	NAC	Nbr or Reflow Cycles		Terminal Plating	NAC		
Preheat Min Temp		Nbr of Instances	0	Component Temp Spike		Shape	NAC		
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Sub-Item	1	ADAPTER P&P, MODU II PIN HDR, DBL, SMD				1.0	179.0	mg	
Material	2	PCT-GF20				1.0	179.0	mg	
Substance	3	Ethene, homopolymer	Supplier	9002-88-4	0.318	1.0	0.56922	mg	
Substance	3	Talc (Mg3H2(SiO3)4)	Supplier	14807-96-6	2.0	1.0	3.58	mg	
Substance	3	Carbon black	Supplier	1333-86-4	0.212	1.0	0.37948	mg	
Substance	3	2,4,8,10-Tetraoxa-3,9-diphosphaspiro [5.5]undecane, 3,9-bis[2,4-bis(1,1-dimethylethyl)phenoxy]-	Supplier	26741-53-7	0.3	1.0	0.537	mg	
Substance	3	Poly(oxy-1,2-ethanediyl),a-(1-oxododecyl)-w-[(1-oxododecyl)oxy]-	Supplier	9005-02-1	4.3	1.0	7.697	mg	
Substance	3	Ethene, homopolymer, oxidized	Supplier	68441-17-8	0.5	1.0	0.895	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	1.0	1.0	1.79	mg	

Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	19.0	1.0	34.01	mg	
Substance	3	Benzene, ethenyl-, homopolymer, brominated	Supplier	88497-56-7	18.0	1.0	32.22	mg	
Substance	3	Antimonate (SbO3 ¹⁻), sodium (1:1)	Supplier	15432-85-6	4.5	1.0	8.055	mg	
Substance	3	Benzenepropionic acid, 3,5-bis(1,1-dimethylethyl)-4-hydroxy-, 1,1-[2-[[3-[3,5-bis(1,1-dimethylethyl)-4-hydroxyphenyl]-1-oxopropoxy]methyl]-2-(hydroxymethyl)-1,3-propanediyl] ester	Supplier	84633-54-5	0.0030	1.0	0.00537	mg	
Substance	3	1,4-Benzenedicarboxylic acid, 1,4-dimethyl ester, polymer with 1,4-cyclohexanedi methanol	Supplier	25135-20-0	49.0	1.0	87.71	mg	
Substance	3	Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	Supplier	29690-82-2	0.57	1.0	1.0203	mg	
Substance	3	Benzenepropionic acid, 3,5-bis(1,1-dimethylethyl)-4-hydroxy-, 1,1-[2-bis[[3-[3,5-bis(1,1-dimethylethyl)-4-hydroxyphenyl]-1-oxopropoxy]methyl]-1,3-propanediyl] ester	Supplier	6683-19-8	0.297	1.0	0.53163	mg	
Sub-Item	1	2X5P MODUII BREAK AWAY HEADER, SMD				1.0	670.26753	mg	
Material	2	Gold Plate				1.0	0.75	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	1.0	0.74775	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	1.0	0.00225	mg	
Material	2	Brass Wire				1.0	433.0	mg	
Substance	3	Copper	Supplier	7440-50-8	71.5	1.0	309.595	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	0.00433	mg	
Substance	3	Zinc	Supplier	7440-66-6	28.0226	1.0	121.33786	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.05	1.0	0.2165	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	1.0	0.00433	mg	
Substance	3	Iron	Supplier	7439-89-6	0.05	1.0	0.2165	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	1.0	0.433	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.0099	1.0	0.042867	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.0433	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.05	1.0	0.2165	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0050	1.0	0.02165	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	0.002165	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	1.0	0.866	mg	
Material	2	Palladium-Nickel Plate				1.0	0.4	mg	
Substance	3	Palladium	Supplier	7440-05-3	80.0	1.0	0.32	mg	
Substance	3	Nickel	Nickel	7440-02-0	20.0	1.0	0.08	mg	
Material	2	Nickel Plate				1.0	4.10692	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.00821384	mg	

Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.00410692	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	1.0	4.0946	mg	
Material	2	PCT-GF20				1.0	230.0	mg	
Substance	3	Ethene, homopolymer	Supplier	9002-88-4	0.318	1.0	0.7314	mg	
Substance	3	Talc (Mg3H2(SiO3)4)	Supplier	14807-96-6	2.0	1.0	4.6	mg	
Substance	3	Carbon black	Supplier	1333-86-4	0.212	1.0	0.4876	mg	
Substance	3	2,4,8,10-Tetraoxa-3,9-diphosphaspiro [5.5]undecane, 3,9-bis[2,4-bis(1,1-dimethylethyl)phenoxy]-	Supplier	26741-53-7	0.3	1.0	0.69	mg	
Substance	3	Poly(oxy-1,2-ethanediyl),a-(1-oxododecyl)-w-[(1-oxododecyl)oxy]-	Supplier	9005-02-1	4.3	1.0	9.89	mg	
Substance	3	Ethene, homopolymer, oxidized	Supplier	68441-17-8	0.5	1.0	1.15	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	1.0	1.0	2.3	mg	
Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	19.0	1.0	43.7	mg	
Substance	3	Benzene, ethenyl-, homopolymer, brominated	Supplier	88497-56-7	18.0	1.0	41.4	mg	
Substance	3	Antimonate (SbO3 ¹⁻), sodium (1:1)	Supplier	15432-85-6	4.5	1.0	10.35	mg	
Substance	3	Benzenepropanoic acid, 3,5-bis(1,1-dimethylethyl)-4-hydroxy-, 1,1-[2-[[3-[3,5-bis(1,1-dimethylethyl)-4-hydroxyphenyl]-1-oxopropoxy]methyl]-2-(hydroxymethyl)-1,3-propanediyl] ester	Supplier	84633-54-5	0.0030	1.0	0.0069	mg	
Substance	3	1,4-Benzenedicarboxylic acid, 1,4-dimethyl ester, polymer with 1,4-cyclohexanedi methanol	Supplier	25135-20-0	49.0	1.0	112.7	mg	
Substance	3	Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	Supplier	29690-82-2	0.57	1.0	1.311	mg	
Substance	3	Benzenepropanoic acid, 3,5-bis(1,1-dimethylethyl)-4-hydroxy-, 1,1-[2,2-bis[[3-[3,5-bis(1,1-dimethylethyl)-4-hydroxyphenyl]-1-oxopropoxy]methyl]-1,3-propanediyl] ester	Supplier	6683-19-8	0.297	1.0	0.6831	mg	
Material	2	Tin Plate				1.0	2.01061	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	0.0020086	mg	
Substance	3	Tin	Supplier	7440-31-5	99.9001	1.0	2.0086	mg	